**Product End-of-Life Disassembly Instructions**

**Product Category:** Monitors and Displays

**Marketing Name / Model**
[List multiple models if applicable.]

OMEN X 27

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

**1.0 Items Requiring Selective Treatment**

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm I/F Board<em>1, Audio Board</em>1, Control Board<em>1, LED Board</em>1</td>
<td>4</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by <em>(check all that apply with an “x” inside the “[ ]”)</em>: [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain [ ]</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps panel*1</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>In adapter</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>HDMI cable<em>1, DP cable</em>1, USB cable<em>1, Power cord</em>1, Adapter*1,</td>
<td>5</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

HPI instructions for this template are available at [EL-MF877-01](#).
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw driver</td>
<td>1</td>
</tr>
<tr>
<td>Hexagon Screw Driver</td>
<td>0</td>
</tr>
<tr>
<td>Flathead screwdriver</td>
<td>1</td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove stand by quick release button to separate the stand and monitor head.
2. Use tool to separate rear cover from monitor head through tear down slot.
3. Use tool to release screw from bucket, then separate bucket and trim from monitor head by hand. Separate top corner first then pull up the bucket to separate bucket and SHD.
4. Use tool to release screws on SHD, then separate the SHD from monitor head, separate the mylar and thermal pad which on the SHD. Release two screws on the SHD to separate the release button and springs.
5. Tear the tape from lamp wire, motor wire, color sensor wire, then disassemble the lamp wire, motor wire, color sensor wire, LVDS FFC*4 and ctrl-BD FFC from connector.
6. Release screws on the power board and interface board, then disassemble power-BD and interface-BD from the chassis.
7. Separate the front bezel from the panel, then use tool to release screws to disassemble ctrl-BD and separate the button and lens from the bezel.
8. Tear the AL-tape on the middle-top side and release side mount screws(*4) to separate chassis and panel, then disassemble the LVDS FFC and lamp wire from the panel by hand.
9. Separate the colorimeter module from top side on the monitor head by hand.
10. To separate colorimeter module, release screw which on the bracket, then remove the motor, worm, arm. Disassemble the arm to the front and back cover and remove the color sensor board from the front cover. Remove the position sensor board from the bracket.
11. Remove the battery which is on the interface board.
12. Remove the gasket, thermal pad and tape on the chassis.
13. Use tool to release screws and separate base
14. Use tool to release screws and separate base cover.
15. Use tool to release screws and separate VESA from stand
16. Use tool to release screws and separate the back cover from stand.
17. Use tool to release screws and separate hinge module.
18. Use tool to release screws and separate QR button.
19. Use tool to release screws and separate lift POM and front cover.
20. Use tool to release screws and separate hinge shield.
21. Use tool to release screws and separate constant force springs from hinge shield.
22. Use tool to release screws and separate the site of constant force springs.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Step 1: Press quick release button to separate head and stand.
Step 2: Use screwdriver to loosen the two screws and disassemble the rear cover.
Step 3: Use flathead screwdriver to stick up rear cover bottom and stick up upper-left, upper-right corner with hands, and then open the rear cover.

Step 4: Remove conductive tape and unplug 2 cable.
Step 5: Remove the conductive and insulating tape and the screw on the hinge.

Step 6: Unplug lamp wire, eDP cable from connector, and take out ambient light board.
Step 7: Unplug ambient light wire from the connector and loosen 4 screws on PCBs.
Step 8: Remove all the gaskets, thermal pad, mylar, spacer on shielding. Remove all cable on PCBs.
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Template Revision C

Last revalidation date 09-May-2018

HPI instructions for this template are available at EL-MF877-01
Step 9: Loosen 16 screws on middle frame to remove the deco and panel.
HPI instructions for this template are available at EL-MF877-01
Step 10: Loosen 4 screws on rear cover to remove the ctrl board and audio board, disassemble the RC lens.

Step 11: Remove 2 LOGO on the rear cover.
Step 12: Remove the lens on the deco.

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Template Revision C

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HPI instructions for this template are available at EL-MF877-01
Step 13: Remove the screws form column, and separate plastic part.
Step 14: Remove cable clip.
Step 15: Remove the screw from hook, and remove hook.
Step 16: Remove the screw from BKT, and remove life module, and disassemble lift module.

Step 17: Remove the rubber from base.